

General Description

The MY9435 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

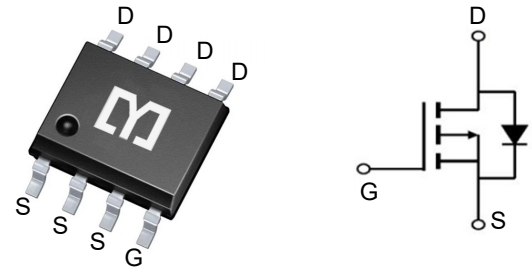


Features

V_{DSS}	-30	V
I_D	-5.3	A
$R_{DS(ON)}$ (at $V_{GS} = -10V$)	36	$m\Omega$
$R_{DS(ON)}$ (at $V_{GS} = -4.5V$)	48	$m\Omega$

Application

- Green Device Available
- Super Low Gate Charge
- Excellent CdV/dt effect decline



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY9435	SOP-8	MY9435	3000

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ\text{C}$	Drain Current ³ , V_{GS} @ 10V	-5.3	A
$I_D@T_A=70^\circ\text{C}$	Drain Current ³ , V_{GS} @ 10V	-4.7	A
I_{DM}	Pulsed Drain Current ¹	-20	A
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	55	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V_{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V _{DS} = -30V, V _{GS} = 0V	-	-	-1	μA
Gate-Source Leakage	I_{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Gate-Source Threshold voltage	V_{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.5	-2.5	V
Drain-Source on-State Resistance ³	R_{DS(on)}	V _{GS} = -10V, I _D = -4.1A	-	36	44	mΩ
		V _{GS} = -4.5V, I _D = -3A	-	48	62	
Dynamic Characteristics⁴						
Input Capacitance	C_{iss}	V _{GS} = 0V , V _{DS} = -15V, f = 1.0MHz	-	530	-	pF
Output Capacitance	C_{oss}		-	70	-	
Reverse Transfer Capacitance	C_{rss}		-	56	-	
Switching Characteristics⁴						
Total Gate Charge	Q_g	V _{GS} = -10V, V _{DS} = -15V, I _D = -4.1A	-	6.8	-	nC
Gate-Source Charge	Q_{gs}		-	1.0	-	
Gate-Drain Charge	Q_{gd}		-	1.4	-	
Turn-on Delay Time	t_{d(on)}	V _{GS} = -10V, V _{DS} = -15V , R _L = 15Ω,R _{GEN} = 2.5Ω	-	14	-	ns
Rise Time	t_r		-	61	-	
Turn-off Delay time	t_{d(off)}		-	19	-	
Fall Time	t_f		-	10	-	
Source-Drain Body Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	I _S = -4.1A, V _{GS} = 0V	-	-	-1.2	V
Continuous Source Current	I_S		-	-	-5.3	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C.
2. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
3. Pulse Test: Pulse width≤300μs, duty cycles≤2%.
4. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical and Thermal Characteristics

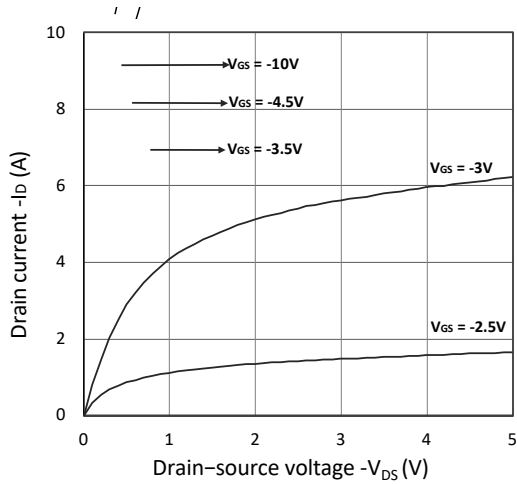


Figure 1. Output Characteristics

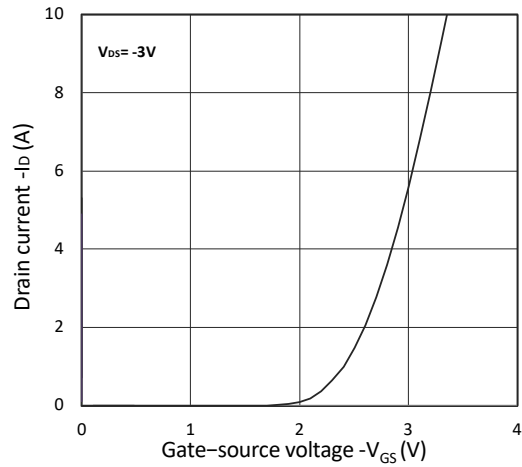


Figure 2. Transfer Characteristics

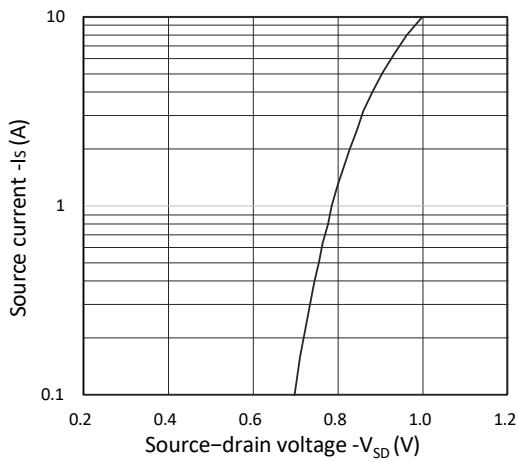


Figure 3. Forward Characteristics of Reverse

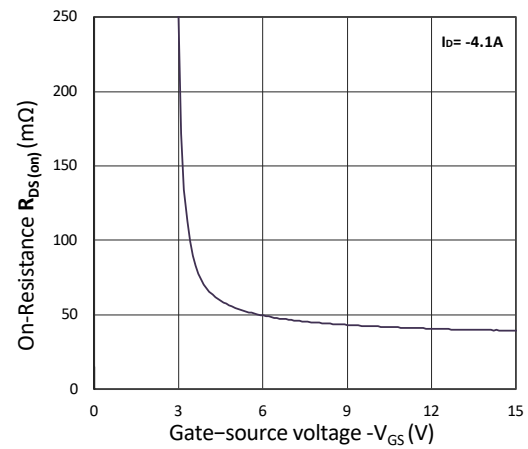


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

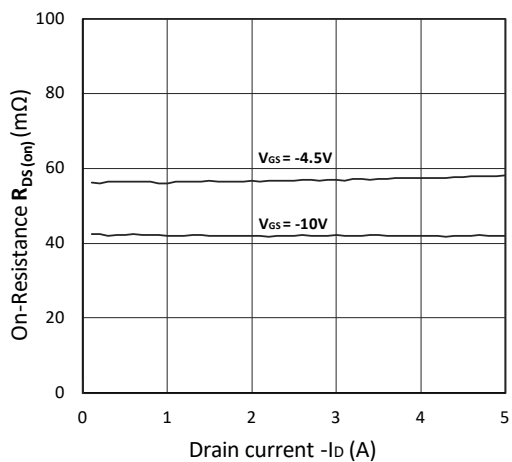


Figure 5. $R_{DS(ON)}$ vs. I_D

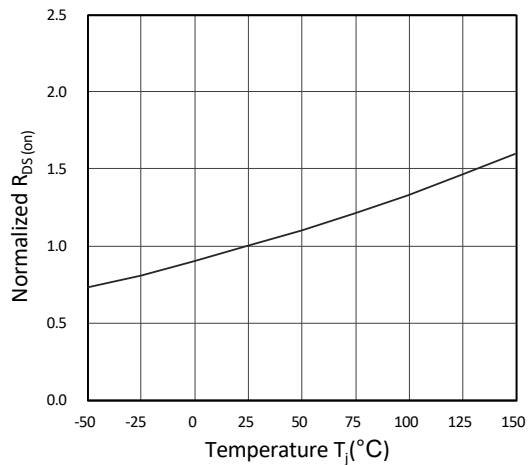


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

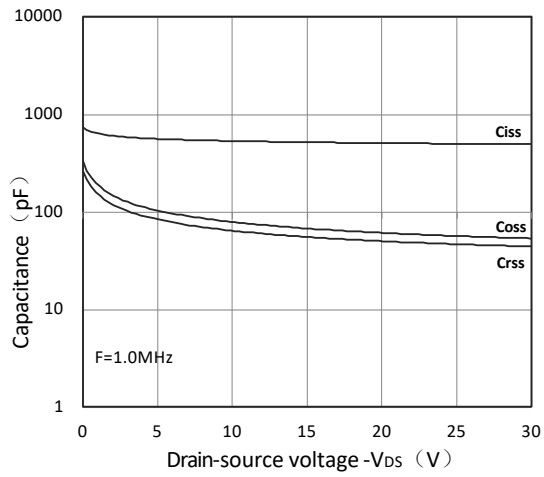


Figure 7. Capacitance Characteristics

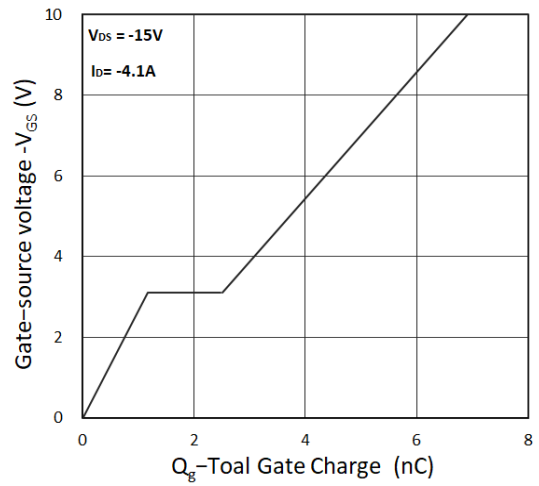
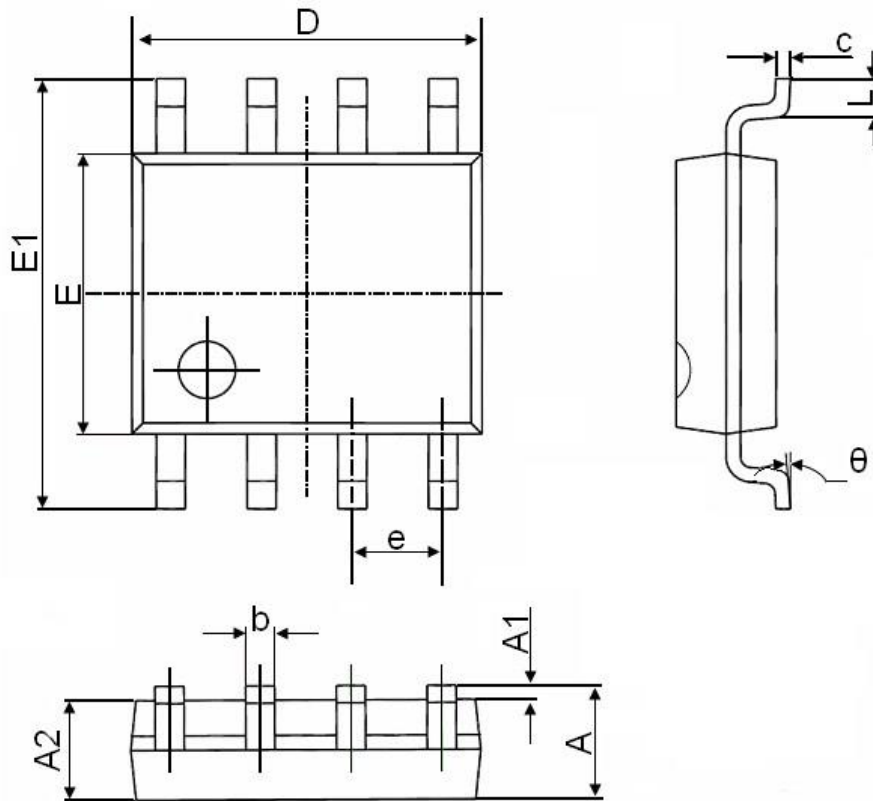


Figure 8. Gate Charge Characteristics

Package Mechanical Data-SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050